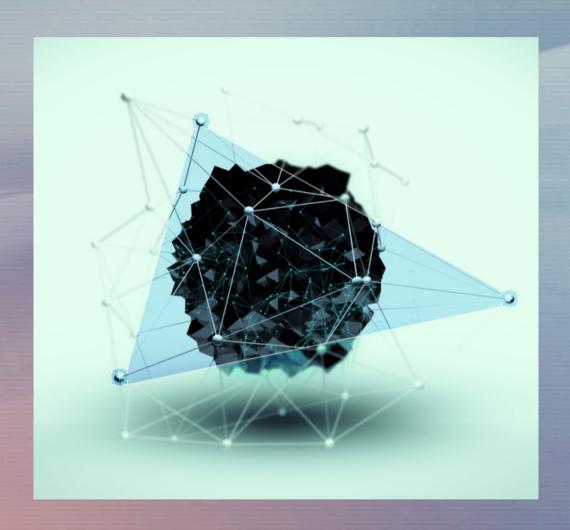


Advances in Materials Physics and Chemistry





Journal Editorial Board

ISSN: 2162-531X (Print) ISSN: 2162-5328 (Online) http://www.scirp.org/journal/ampc

.....

Editor-in-Chief

Prof. Zhiwen Chen Shanghai University, China

Editorial Board

Dr. Bensely AlbertCMC Americas, Inc., USAProf. Adriana BigiUniversity of Bologna, Italy

Prof. Luigi Maxmilian Caligiuri University and Scientific Research, Italy

Dr. Mary Caruso 3M Company, USA

Prof. Changle Chen University of Science & Technology of China, China

Dr. Tien-Min Gabriel Chu Indiana University School of Dentistry, USA

Dr. Byron D. Gates Simon Fraser University, Canada

Dr. A. Nirmala Grace VIT University, India

Prof. David Hui University of New Orleans, USA

Dr. Mika Veli Juhani Hukkanen University of Helsinki, Finland

Prof. Kisuk Kang Seoul National University, South Korea

Dr. Hong Jin Kim Advanced Module Engineering, Globalfoundries, USA

Dr. Ing Kong RMIT University, Malaysia

Prof. Mathew T. Mathew Rush University Medical Centre, USA

Prof. Santosh K. Pandey Iowa State University, USA

Prof. Rakesh Sharma FAMU-FSU College of Engineering, USA

Prof. Yadong Wang University of Pittsburgh School of Medicine, USA

Prof. Meng ZhangPhilips Lumileds Lighting Company, USAProf. Qifa ZhouUniversity of Southern California, USA



Table of Contents

Volume 5	Number 12	December 2015
Preparation of PDOT:PSS Transparent Conductive Film Using Ink-Jet Printing		
A. Nitta, K. S	nimono	467

Advances in Materials Physics and Chemistry (AMPC)

Journal Information

SUBSCRIPTIONS

The Advances in Materials Physics and Chemistry (Online at Scientific Research Publishing, www.SciRP.org) is published monthly by Scientific Research Publishing, Inc., USA.

Subscription rates:

Print: \$79 per issue.

To subscribe, please contact Journals Subscriptions Department, E-mail: sub@scirp.org

SERVICES

Advertisements

Advertisement Sales Department, E-mail: service@scirp.org

Reprints (minimum quantity 100 copies)

Reprints Co-ordinator, Scientific Research Publishing, Inc., USA.

E-mail: sub@scirp.org

COPYRIGHT

COPYRIGHT AND REUSE RIGHTS FOR THE FRONT MATTER OF THE JOURNAL:

Copyright © 2015 by Scientific Research Publishing Inc.

This work is licensed under the Creative Commons Attribution International License (CC BY). http://creativecommons.org/licenses/by/4.0/

COPYRIGHT FOR INDIVIDUAL PAPERS OF THE JOURNAL:

Copyright © 2015 by author(s) and Scientific Research Publishing Inc.

REUSE RIGHTS FOR INDIVIDUAL PAPERS:

Note: At SCIRP authors can choose between CC BY and CC BY-NC. Please consult each paper for its reuse rights.

DISCLAIMER OF LIABILITY

Statements and opinions expressed in the articles and communications are those of the individual contributors and not the statements and opinion of Scientific Research Publishing, Inc. We assume no responsibility or liability for any damage or injury to persons or property arising out of the use of any materials, instructions, methods or ideas contained herein. We expressly disclaim any implied warranties of merchantability or fitness for a particular purpose. If expert assistance is required, the services of a competent professional person should be sought.

PRODUCTION INFORMATION

For manuscripts that have been accepted for publication, please contact:

E-mail: ampc@scirp.org





Advances in Materials Physics and Chemistry

ISSN: 2162-531X (Print) ISSN: 2162-5328 (Online)

http://www.scirp.org/journal/ampc

Advances in Materials Physics and Chemistry contains rapid communications, full-length original research, review articles and comments on interrelationships among synthesis, micro/nanostructures, properties, processing and performance of Materials Science, Physics, and Chemistry. This includes, but is not limited to:

- Biomaterials
- Composite Materials
- Energy Resources Materials
- Environmental Materials
- Fine Ceramics
- · Graphene and Carbon
- Magnetics
- Nanodevices
- Nanomaterials
- Nanotechnology
- Optoelectronic Materials
- Polymers
- Quantum Science and Technology
- Semiconductors
- Superconductors
- Surface and Interface Science
- Thin Films

Editor-in-Chief

Prof. Zhiwen Chen Shanghai University, China

Editorial Board

Dr. Bensely Albert Prof. Adriana Bigi

Prof. Luigi Maxmilian Caligiuri

Dr. Mary Caruso Prof. Changle Chen Dr. Tien-Min Gabriel Chu

Dr. Byron D. Gates

Dr. A. Nirmala Grace

Prof. David Hui

Dr. Mika Veli Juhani Hukkanen

Prof. Kisuk Kang Dr. Hong Jin Kim

Dr. Ing Kong Prof. Mathew T. Mathew Prof. Santosh K. Pandey Prof. Rakesh Sharma

Prof. Yadong Wang Prof. Meng Zhang Prof. Qifa Zhou

Website and E-Mail

http://www.scirp.org/journal/ampc

E-mail: ampc@scirp.org